

Plaskon NXG-1FP

Epoxy; Epoxide

Cookson Electronics - Semiconductor Products

Message:

This material is an epoxy molding compound for high temperature, lead-free reflow in fine pitch applications. It is designed to withstand more demanding requirements in moisture performance, occasioned by the higher IR reflow temperatures required for processing lead-free packages. It is a highly filled, hybrid resin developed to pass JEDEC Level 2A at 260°C IR reflow temperature. It is a "green" compound with no halogens and a lower Tg than multifunctional materials.

General Information			
Features	Semi-conductive		
	Low (to no) lead content		
	Low hygroscopicity		
	Fast curing		
	Good formability		
	Heat resistance, high		
	Halogen-free		
Forms	Liquid		
Processing Method	Resin transfer molding		
Physical	Nominal Value	Unit	Test Method
Specific Gravity	1.97	g/cm ³	ASTM D792
Mechanical	Nominal Value	Unit	Test Method
Flexural Modulus			ASTM D790
22°C	2.26	MPa	ASTM D790
260°C	0.0686	MPa	ASTM D790
Flexural Strength			ASTM D790
22°C	0.0126	MPa	ASTM D790
260°C	8.63E-4	MPa	ASTM D790
Thermal	Nominal Value	Unit	Test Method
Glass Transition Temperature	150	°C	ASTM E1356
CLTE - Flow	1.2E-5	cm/cm/°C	ASTM D696
Thermal Conductivity	0.70	W/m/K	ASTM C177
Flammability	Nominal Value		Test Method
Flame Rating (3.18 mm)	V-0		UL 94
Additional Information			
Recommended Storage Temperature: <5°C Life @ 5°C, defined as not more than 40% loss of spiral flow based on original values.: 6 months Life @ 22°C, defined as not more than 40% loss of spiral flow based on original values.: 2 days Life @ 35°C, defined as not more than 40% loss of spiral flow based on original values.: 0.5 days Spiral Flow, 175°C, 1000 psi: 180 cm Shimadzu Viscosity, 175°C, 1000 psi: 40 poise Ram Follower Gel Time, 175°C, 1000 psi: 18 sec Ash Content: 87 % Hydrolyzable Halides: <1 ppm Moisture Absorption, 85°C/85%RH, 168 hrs: 0.3% Cull Hot Hardness, Shore D: 75 All test specimens are transfer molded and post cured for 4 hours at 175°C Linear Thermal Expansion, Alpha 1: 11.5 cm ⁻⁶ /cm/°C Linear Thermal Expansion, Alpha 2: 42 cm ⁻⁶ /cm/°C			

Injection instructions

Resin Transfer Molding:

Molding Temperature: 165 to 185°C

Molding Pressure: 1000 psi

In Mold Cure Time: 50 to 100 sec

Post Mold Cure Time, 175°C: 0 to 2 hr

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